

- State-of-the-Art **EPIC-IIIB™** BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- High-Impedance State During Power Up and Power Down
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Package Options Include Plastic Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

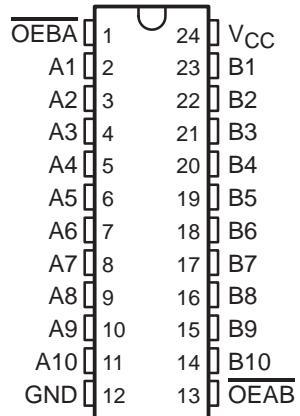
The 'ABT861 are 10-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices allow noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

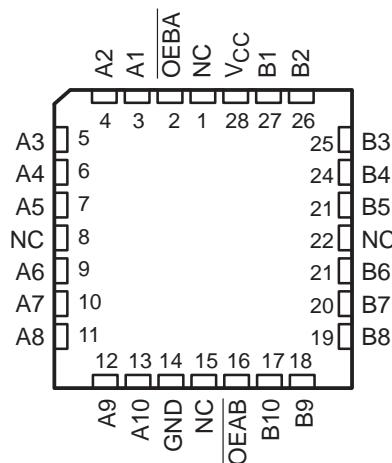
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT861 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT861 is characterized for operation from -40°C to 85°C .

SN54ABT861 . . . JT PACKAGE
SN74ABT861 . . . DW OR NT PACKAGE
(TOP VIEW)



**SN54ABT861 . . . FK PACKAGE
(TOP VIEW)**



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

UNLESS OTHERWISE NOTED this document contains PRODUCTIVE DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS
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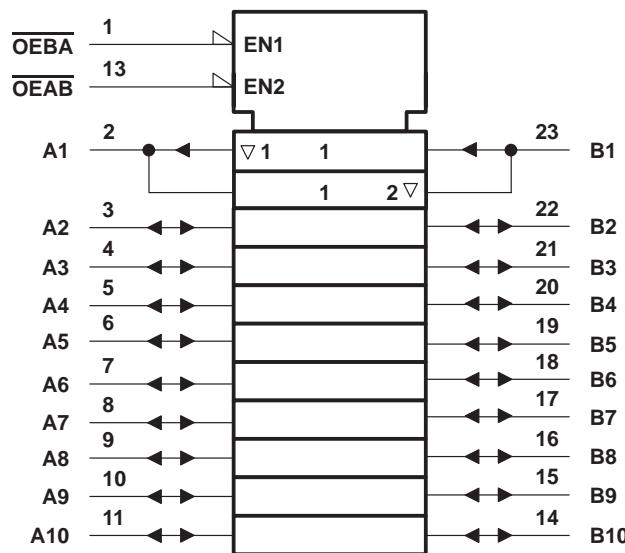
SN54ABT861, SN74ABT861 10-BIT TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS199C – FEBRUARY 1991 – REVISED MAY 1997

FUNCTION TABLE

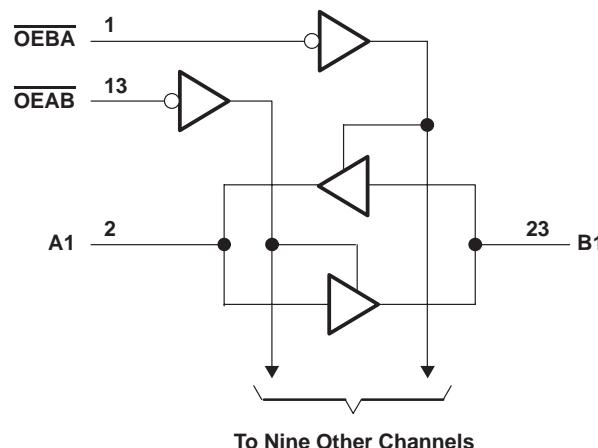
INPUTS		OPERATION
OEAB	OEBA	
L	H	A data to B bus
H	L	B data to A bus
H	H	Isolation
L	L	Latch A and B (A = B)

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT861		SN74ABT861		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		-24		-32	mA
I _{OL}	Low-level output current		48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		5	5	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

SN54ABT861, SN74ABT861

10-BIT TRANSCEIVERS

WITH 3-STATE OUTPUTS

SCBS199C – FEBRUARY 1991 – REVISED MAY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TA = 25°C			SN54ABT861		SN74ABT861		UNIT
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
VIK	VCC = 4.5 V, I _I = -18 mA			-1.2		-1.2		-1.2	V
V _{OH}	VCC = 4.5 V, I _{OH} = -3 mA	2.5		2.5		2.5			V
	VCC = 5 V, I _{OH} = -3 mA	3		3		3			
	VCC = 4.5 V	I _{OH} = -24 mA	2		2				
		I _{OH} = -32 mA	2*				2		
V _{OL}	VCC = 4.5 V	I _{OL} = 48 mA		0.55		0.55			V
		I _{OL} = 64 mA		0.55*			0.55		
V _{hys}			100						mV
I _I	Control inputs	VCC = 5.5 V, V _I = VCC or GND		±1		±1		±1	µA
	A or B ports			±100		±100		±100	
I _{OZPU} ‡	VCC = 0 to 2.1 V, V _O = 0.5 V to 2.7 V, OE = X			±50		±50		±50	µA
I _{OZPD} ‡	VCC = 2.1 V to 0, V _O = 0.5 V to 2.7 V, OE = X			±50		±50		±50	µA
I _{OZH} §	VCC = 5.5 V, V _O = 2.7 V			50		50		50	µA
I _{OZL} §	VCC = 5.5 V, V _O = 0.5 V			-50		-50		-50	µA
I _{off}	VCC = 0, V _I or V _O ≤ 4.5 V			±100				±100	µA
I _{CEX}	VCC = 5.5 V, V _O = 5.5 V	Outputs high		50		50		50	µA
I _O ¶	VCC = 5.5 V, V _O = 2.5 V		-50 -100 -225#		-50 -225#		-50 -225#		mA
I _{CC}	A or B ports	VCC = 5.5 V, I _O = 0, V _I = VCC or GND	Outputs high	1	250		250		µA
			Outputs low	24	38		38		mA
			Outputs disabled	0.5	250		250		µA
ΔI _{CC}	Data inputs	VCC = 5.5 V, One input at 3.4 V, Other inputs at VCC or GND	Outputs enabled		1.5		1.5		mA
			Outputs disabled		1.5#		1.5#		
	Control inputs	VCC = 5.5 V, One input at 3.4 V, Other inputs at VCC or GND		1.5		1.5		1.5	
C _i	Control inputs	V _I = 2.5 V or 0.5 V		4.5					pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V		10.5					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at VCC = 5 V.

‡ This parameter is characterized, but not production tested.

§ The parameters I_{OZH} and I_{OZL} include the input leakage current.

¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This limit may vary among suppliers.

|| This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

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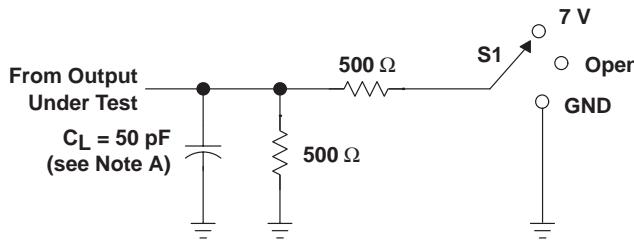
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$			SN54ABT861	SN74ABT861	UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	3.4	4.9	1	5.3	1 5.2
t_{PHL}			1	3.2	4.4	1	5	1 4.9†
t_{PZH}	\overline{OEAB} or \overline{OEBA}	B or A	1	3.5	5	1	6	1 5.9
t_{PZL}			1	4.6	6	1	7	1 6.9
t_{PHZ}	\overline{OEAB} or \overline{OEBA}	B or A	2.1	5.3	6.5	2.1	7.6	2.1 7.5
t_{PLZ}			1.5	5.3	6.6	1.5	7.2	1.5 7.1

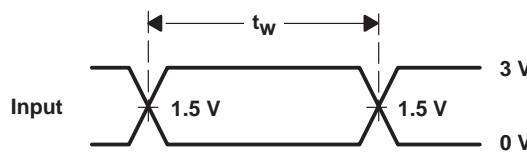
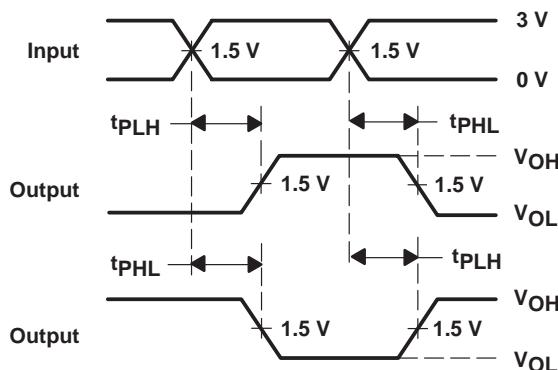
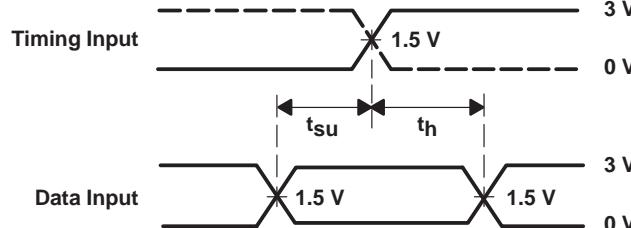
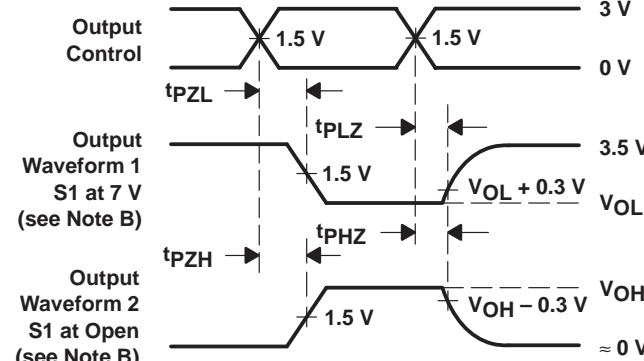
† This limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

LOAD CIRCUIT

VOLTAGE WAVEFORMS
PULSE DURATIONVOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTSVOLTAGE WAVEFORMS
SETUP AND HOLD TIMESVOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABT861DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT861	Samples
SN74ABT861NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT861NT	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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10-Jun-2014

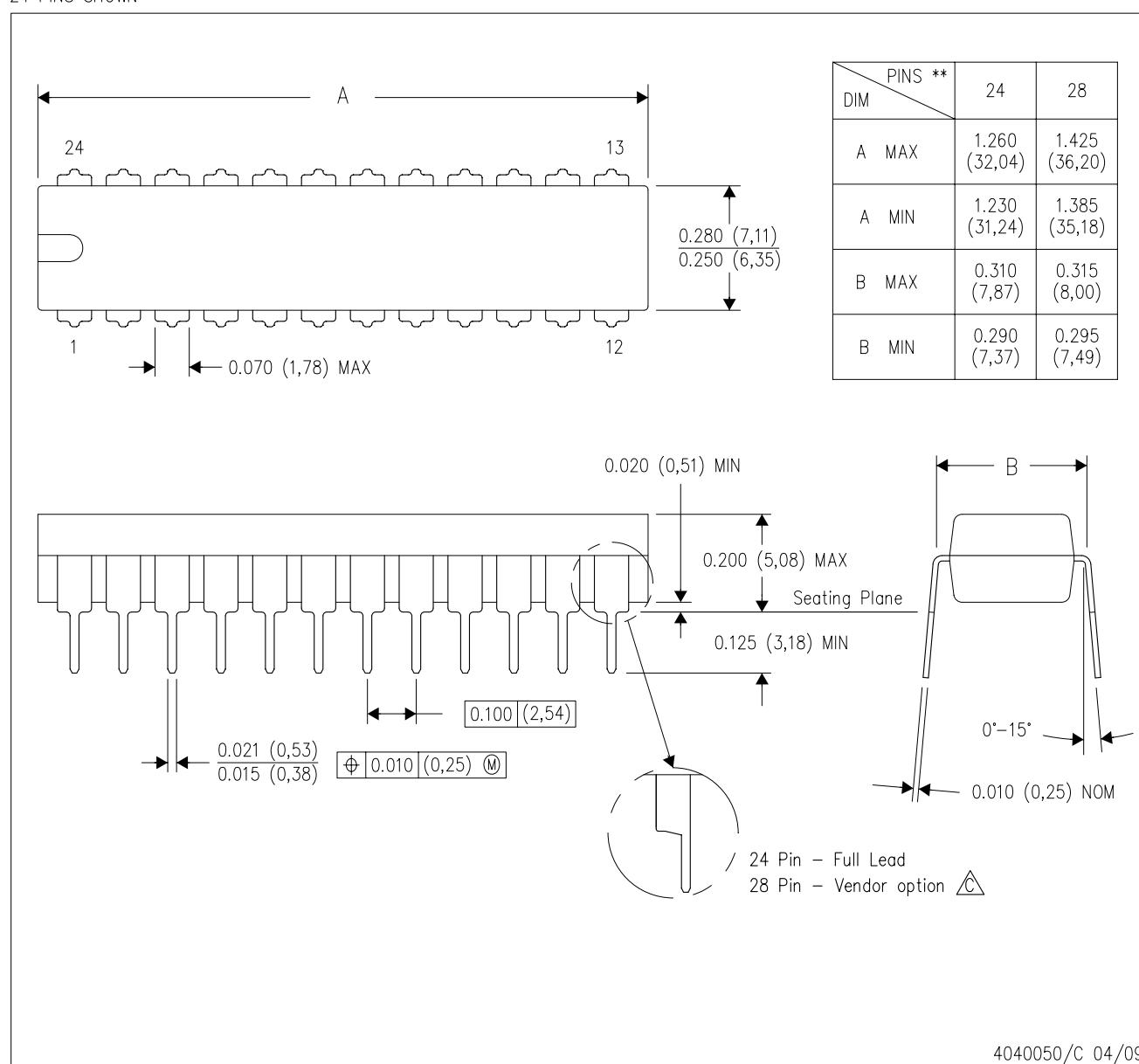
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MECHANICAL DATA

NT (R-PDIP-T**)

24 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



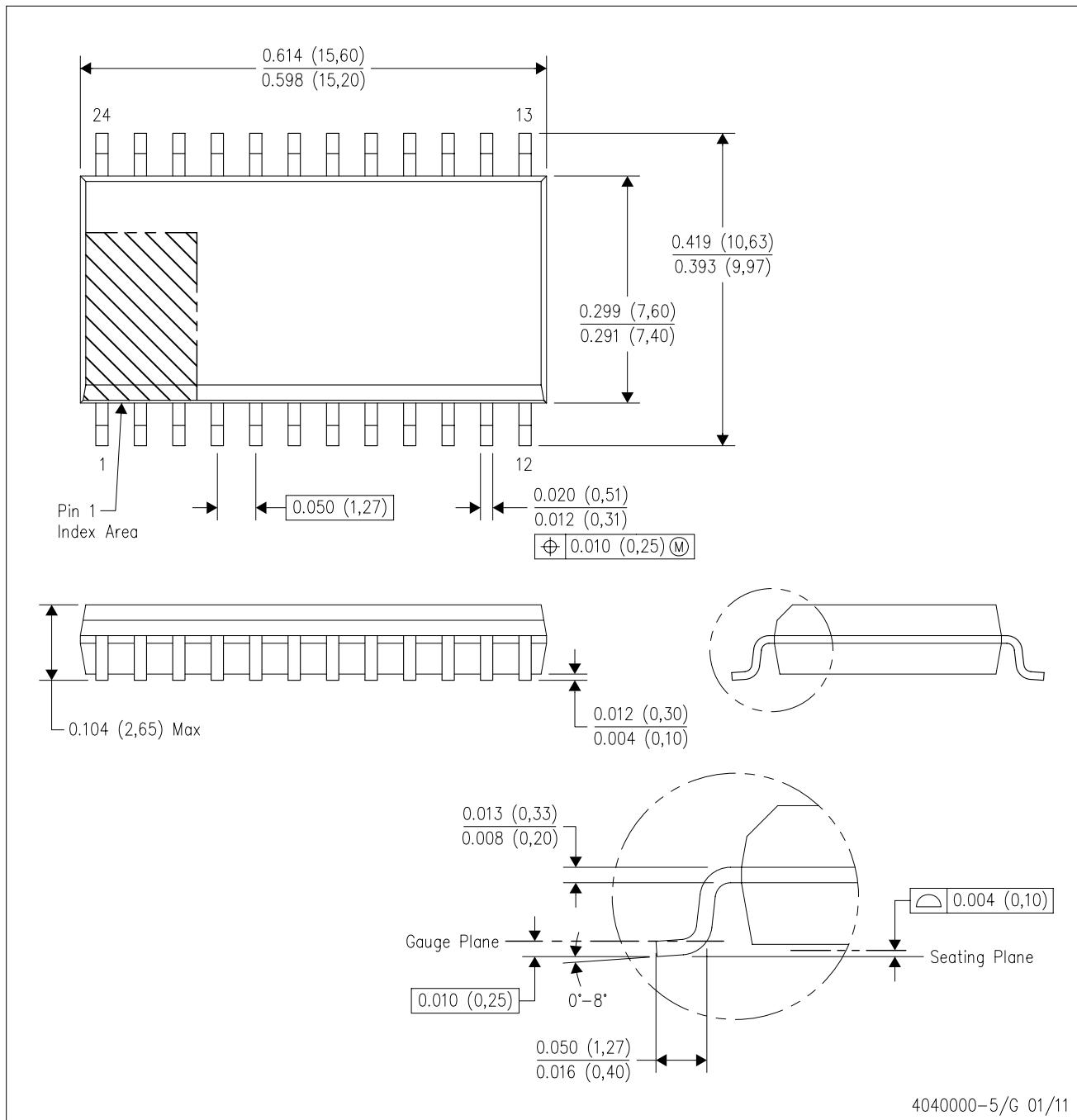
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

\triangle The 28 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

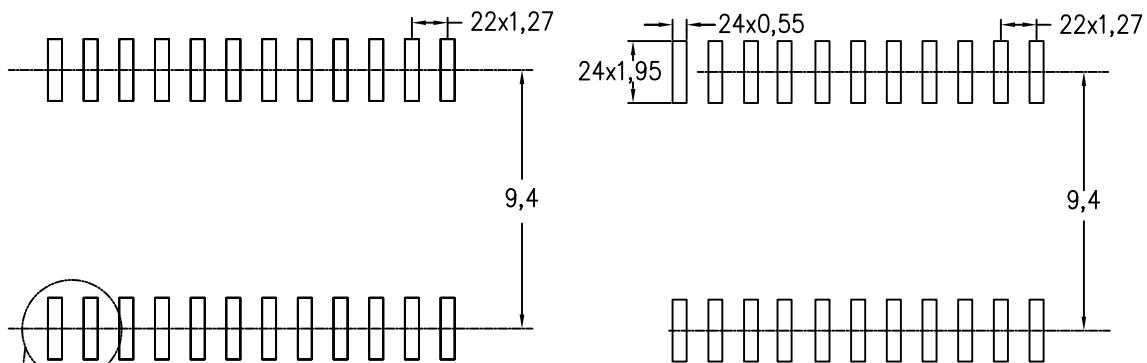


NOTES:

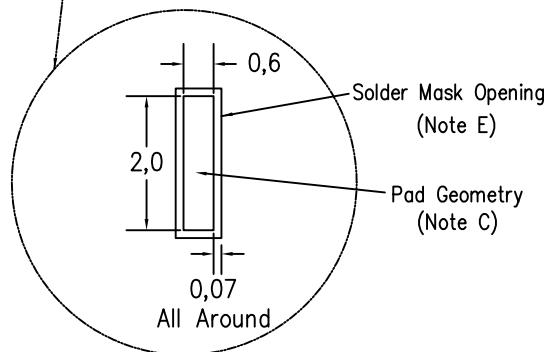
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AD.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)

Non Solder Mask Define Pad



4209202-5/F 08/13

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Refer to IPC7351 for alternate board design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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